

CTT0223, CTT1223, CTT2223, CTT3223

600V Random Phase High Power Photo TRIAC

Features

- High isolation 5000 VRMS
- Supports 0.3 A, 0.6 A, 0.9 A and 1.2 A
- RoHS compliance
- REACH compliance
- External creepage > 7.5mm
- Internal creepage > 6.0mm
- Insulation distance > 0.4mm
- Regulatory Approvals
 - UL UL1577 (E364000)
 - VDE EN60747-5-5(VDE0884-5)
 - CQC GB4943.1, GB8898
 - IEC60065, IEC60950

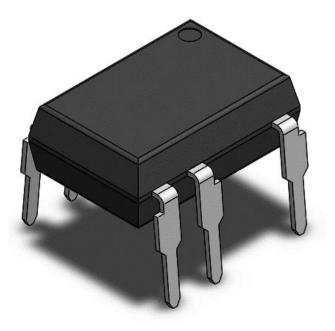
Description

The random phase power Triac consists of a Triac and a photo-Triac, which is optically coupled to a gallium arsenide Infrared emitting diode, and house in a 7-lead DIP package. It also comes with different lead forming options.

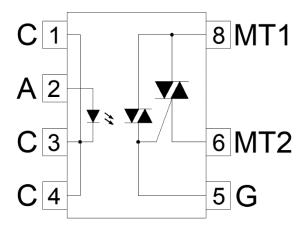
Applications

- Home appliances
- Industrial equipment

Package Outline



Schematic



Note: Different bending options available. See package dimension.



Absolute Maximum Rating at 25°C

Symbol	Parameters		Ratings	Units	Notes
V _{iso}	Isolation voltage		5000	Vrms	
T _{OPR}	Operating temp	perature	-40 ~+85	°C	
T _{STG}	Storage tempe	erature	-40 ~+125	°C	
т.	Soldering temp	perature	260	°C	
T _{SOL}	Wave soldering te	mperature	260	°C	
Emitter				·	
I _F	LED forward o	current	50	mA	
VR	LED reverse v	voltage	6	V	
IFP	Peak forward	current	1	1 A	
Pin	Power dissipation		75	mW	
Detector				·	
V _{DRM}	Repetitive peak OFF	600	V		
	Continuous Current Load	CTT0223	0.3		
		CTT1223	0.6	Α	
I _{T(RMS)}		CTT2223	0.9		
		CTT3223	1.2		
	Peak Current Load	CTT0223	3		
		CTT1223	6	A	
Ітѕм		CTT2223	9		
		CTT3223	12		
Pout	Power dissip	Power dissipation		mW	
PT	Total power dissipation		850	mW	



Electrical Characteristics $T_A = 25$ °C (unless otherwise specified)

Emitter Characteristics

Symbol	Parameters	Test Conditions	Min	Тур	Max	Units	Notes
VF	Forward voltage	I _F =10mA	-	-	1.3	V	
I _R	Reverse Current	V _R = 6V	-	-	5	μΑ	
Cin	Input Capacitance	f= 1MHz	-	45	-	pF	

Detector Characteristics

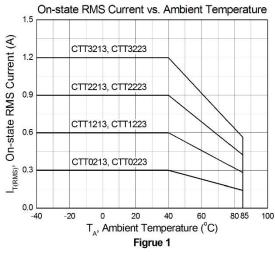
Symbol	Parameters	Test Conditions	Min	Тур	Max	Units	Notes
I _{DRM}	Peak Blocking Current	I _F = 0mA, V _{DRM} = Rated V _{DRM}	-	-	100	uA	
V_{TM}	Peak On-State Voltage	I _F = Rated I _{FT} , I _{TM} = 100mA	-	-	2.5	V	
dv/dt	Critical Rate of Rise off-State Voltage	VPEAK= Rated VDRM	200	-	-	V/μs	

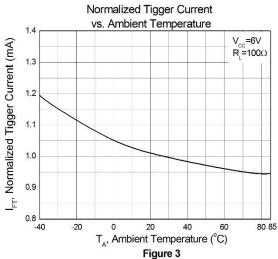
Transfer Characteristics

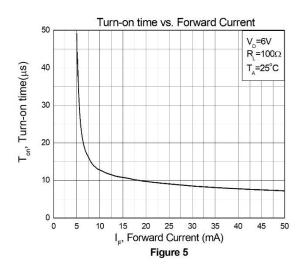
Symbol	Parameters	Test Conditions	Min	Тур	Max	Units	Notes
I _{FT}	Input Trigger Current	Terminal Voltage = 3V	-	-	10	mA	
lн	Holding Current		-	-	25	mA	
Rıo	Isolation Resistance	Vio= 500VDC	1x10 ¹¹	-	-	Ω	
Cıo	Isolation Capacitance	f= 1MHz	-	0.25	-	pF	

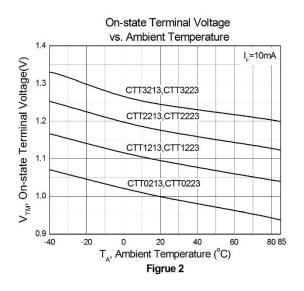


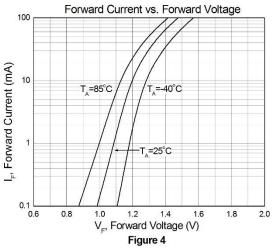
Typical Characteristic Curves

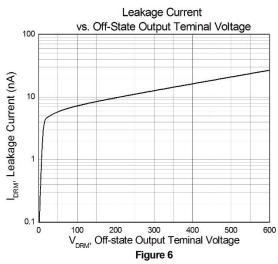




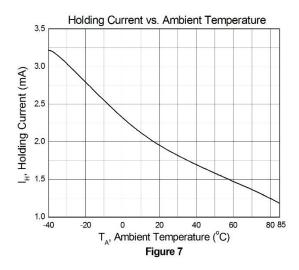








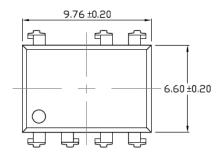


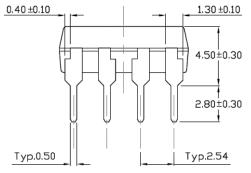


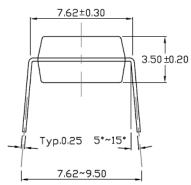


Package Dimension Dimensions in mm unless otherwise stated

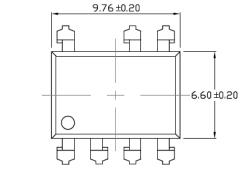
Standard DIP - Through Hole

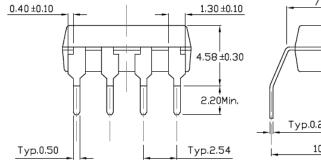






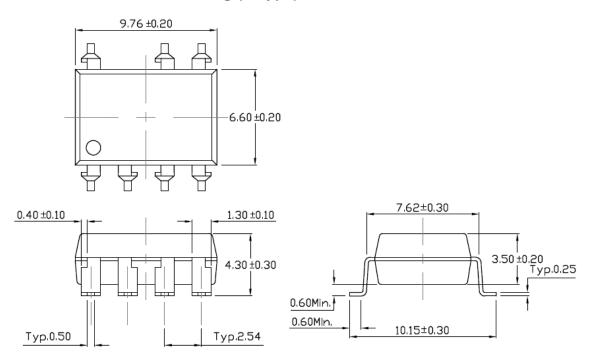
Gullwing (400mil) Lead Forming – Through Hole (M Type)



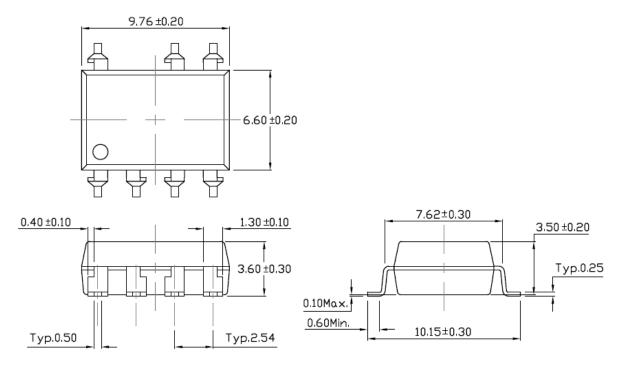




Surface Mount Lead Forming (S Type)

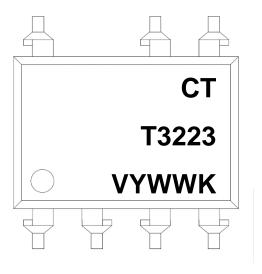


Surface Mount (Low Profile) Lead Forming (SL Type)





Device Marking



Note:

CT : Denotes "CT Micro"

T3223 : Product Number

V : VDE Safety Mark (option)

Y : Fiscal Year WW : Work Week

K : Production Code

Ordering Information

CTTX223(V)(Y)(Z)

CT = Denotes "CT Micro"

TX223 = Product Number (Current Rating Option X=0, 1, 2, or 3)

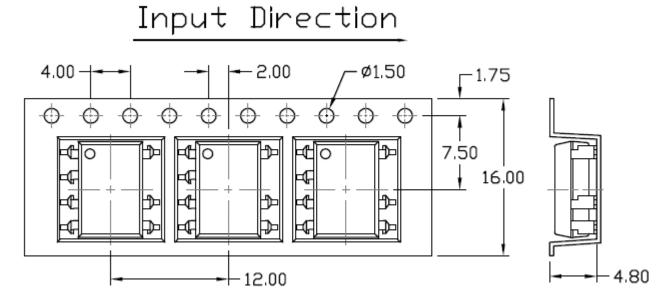
V = VDE safety mark option (V, or none)
 Y = Lead form option (S, SL, M or none)
 Z = Tape and reel option (T1, T2 or none)

Option	Description	Quantity	
None	Standard 8 Pin Dip	40 Units/Tube	
M	Gullwing (400mil) Lead Forming	40 Units/Tube	
S(T1)	Surface Mount Lead Forming – With Option 1 Taping	1000 Units/Reel	
S(T2)	Surface Mount Lead Forming – With Option 2 Taping	1000 Units/Reel	
SL(T1)	Surface Mount (Low Profile) Lead Forming– With Option 1 Taping	1000 Units/Reel	
SL(T2)	Surface Mount (Low Profile) Lead Forming- With Option 2 Taping	1000 Units/Reel	

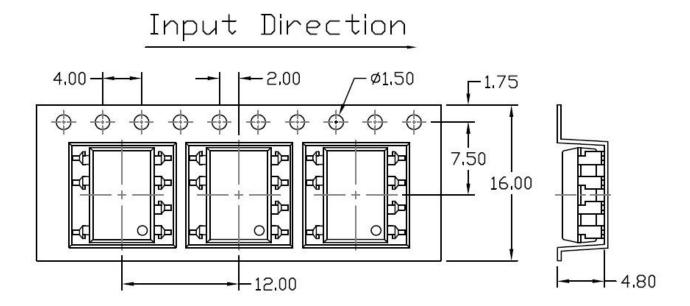


Carrier Tape Specifications Dimensions in mm unless otherwise stated

Option S(T1) & SL(T1)



Option S(T2) & SL(T2)





Wave soldering (JEDEC22A111 compliant)

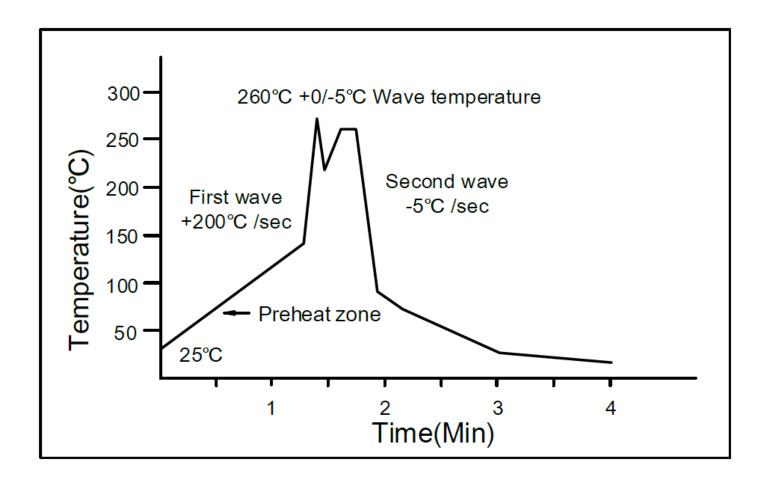
One time soldering is recommended within the condition of temperature.

Temperature: 260+0/-5°C.

Time: 10 sec.

Preheat temperature:25 to 140°C.

Preheat time: 30 to 80 sec.



Hand soldering by soldering iron

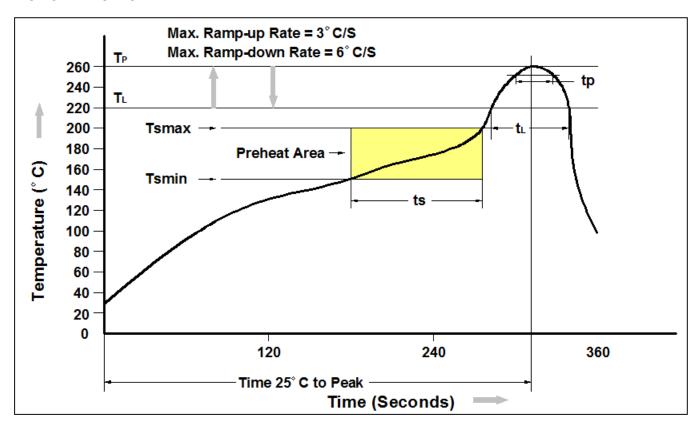
Allow single lead soldering in every single process.

One time soldering is recommended. Temperature: 350+0/-5°C

Time: 3 sec max.



Reflow Profile



Profile Feature	Pb-Free Assembly Profile		
Temperature Min. (Tsmin)	150°C		
Temperature Max. (Tsmax)	200°C		
Time (ts) from (Tsmin to Tsmax)	60-120 seconds		
Ramp-up Rate (t∟ to t⊳)	3°C/second max.		
Liquidous Temperature (T _L)	217°C		
Time (t _L) Maintained Above (T _L)	60 – 150 seconds		
Peak Body Package Temperature	260°C +0°C / -5°C		
Time (t _P) within 5°C of 260°C	30 seconds		
Ramp-down Rate (T _P to T _L)	6°C/second max		
Time 25°C to Peak Temperature	8 minutes max.		



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